

Automotive Electronics Council
Component Technical Committee

Fourth European Automotive Electronics Reliability Workshop

Call for Presentations

October 8 – 9, 2025



Palais de la Bourse - Bordeaux

**17 Place de la Bourse
33076 Bordeaux, France
<https://www.bordeauxpalaisbourse.com/>**

organized by the AEC Technical Committee in cooperation with ESREF 2025*:
** 36th European Symposium on Reliability of Electronic Devices, Failure Physics and Analysis*



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2025 – Fourth European Automotive Electronics Reliability Workshop

October 8-9, 2025
Palais de la Bourse
Bordeaux / France

The Fourth European Automotive Electronics Reliability Workshop will be held at Palais de la Bourse on October 8 and 9, 2025. In total 23 preceding workshops in the US and 3 in Europe, have been providing a forum and structured environment to discuss quality and reliability problems and philosophies related to all aspects of passive components, discrete semiconductor devices, integrated circuit devices, LEDs, wide band gap semiconductor devices, multi-chip modules in terms of design, test, analysis, fabrication, assembly, and field performance. Building upon this rich history, the environment will be a highly interactive technical presentation and panel discussion format promoting open and frank communications within the international automotive component supplier base.

This edition is organized in parallel with 36th ESREF international symposium that focuses on recent developments and future directions in quality and reliability of materials, devices and circuits for micro-, nano-, and optoelectronics. Consequently, there is a possibility to attend symposium sessions as well as to visit the exhibition area during the 2 days' workshop.

Call For Presentations

This call for presentations solicits your submission of abstracts of less than 200 words dealing with current automotive electronic component issues. The abstracts and topics will be reviewed and selected for presentation based upon technical merit, innovation, automotive focus, and relevancy. **Company commercials and/or endorsements are not allowed. Company logos may be used on presentation slide borders only.** Each presentation will be allotted 20-25 minutes, followed by a question and answer session.

Some areas and topics that are relevant to and presented by workshop participants previously are listed below. Items in bold text are those of particular interest for this year's workshop. Works involved in passive components, discrete semiconductor devices, integrated circuit devices, LEDs, wide band gap semiconductor devices, and multi-chip modules are welcome. Presentations and late breaking contributions relevant to today's activities and tomorrow's ideas are also requested.

Q10x/Q200 new revisions - Impact

Field Quality Performance
Accelerated Stresses
Wafer Level Reliability
Product Characterization
Board Level Simulation

MCM qualification/screen

Reliability Simulation
Emerging Challenges
FMEA
Advanced Packaging

Technical Issues with 28nm and below

Influence OEM Automotive Environment
New Failure Analysis Technologies

OEM/End-Customer Requirements

New Test/Screen Techniques
Quality System/Methodology Trends
Reliability Monitoring Usefulness
Burn-In/Test Screen Elimination
Application Specific Qualification
Criteria for Using Non-Automotive Parts
OEM System Reliability
Extended Mission Profile Standardization
Extended Qualification
EOS/ESD/NTF Reduction

New Package Concepts

Flip Chip Packages
Wafer Level Packages

Emerging Technology

Autonomous Driving
Driver Assist/RF/Radar
MEMS
LED's
ISO Specification/ASIL
EMC/Latch-Up
Vehicle Communications/V2V
Internet-of-Things (IoT) in Vehicles
Wide Band Gap Semiconductors

"Zero Defects" Implementation

New/Suspect Failure Mechanisms
Known Good Die (KGD)
Maverick Lot/Wafer Methodology
Design for Test/Mfg/Rel/FA
Safe Launch

Submit an electronic version of your abstract* (in both Word & PDF format) and finished presentation (in both PowerPoint & PDF format) to:

Abstract submission:** aec.registration@hella.com

**add affiliation, email contact, and name of presenting author*

*** for registration details (refer to workshop registration on next page)*

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AEC Objective: The purpose of this workshop is to continuously improve communications between automotive electronic component users and their supplier base. The goal of the Automotive Electronics Council is the development of uniform automotive industry specifications and requirements to improve automotive product quality and reliability while reducing cost and time to market.

Who Should Attend: Engineers and managers who are involved in the qualification, testing, reliability, and failure analysis of automotive passive components, discrete semiconductor devices, integrated circuit devices, LEDs, wide band gap semiconductor devices, and multi-chip modules. It would also be helpful to those who are responsible for establishing quality and reliability policies for automotive components.

Registration Fee: Registration fee is 320 Euros (and includes lunch and breaks for 2 days). The fee is to be paid during registration (see below).

This is your workshop. Please come with an open mind and be prepared to share and learn about new ideas and accomplishments. Your ideas on how to improve future workshops are always welcomed.

Workshop Registration

Registering for the workshop can be done by filling out the registration form on the ESREF website and clearly indicate that you want to attend for the AEC workshop:

<https://congres.adera.fr/congres/ESREF-2025/uk/>

Note (1): you will be requested to use or create an account on “congres.adera.fr”, the platform used by ESREF organizing committee; then register by selecting “AEC-RW Workshop registration fee (€ 320 incl. tax)”

Note (2): only if you also intend to attend the ESREF conference outside the 2-day workshop, register by selecting “ESREF Regular Registration fee (€ 850 incl. tax)” and send an email just with the subject “Registered for ESREF and AEC-RW” to: aec.registration@hella.com. AEC-RW fee is covered by the ESREF fee in that case.

Hotel Reservation

Hotels can be booked via ESREF official travel agency partner “Revolugo”. Details can be found on ESREF website (Conference Venue/Accommodation):

<https://esref2025.sciencesconf.org/resource/page/id/11>

Organizing Committee of AEC-RW 2025

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Tentative Agenda

(subject to change based on abstracts received)

Wednesday, October 8, 2025

8:00 am	-	8:30 am	Registration
8:30 am	-	9:00 am	Welcome
9:00 am	-	10:30 am	Technical Session 1
10:30 am	-	11:00 am	Break
11:00 am	-	11:45 am	Q100
11:45 am	-	12:30 noon	Q200
12:30 noon	-	1:30 pm	Lunch
1:30 pm	-	3:00 pm	Technical Session 2
3:00 pm	-	3:45 pm	Q104
3:45 pm	-	4:15 pm	Break
4:15 pm	-	5:00 pm	Q101
5:00 pm	-	5:45 pm	Wide Band Gap
5:45 pm			Wrap-up day 1

Thursday, October 9, 2025

8:15 am	-	8:30 am	Opening Day 2
8:30 am	-	9:00 am	Q004
9:00 am	-	10:30 am	Technical Session 3
10:30 am	-	11:00 am	Break
11:00 am	-	11:45 noon	Q006
11:45 noon	-	12:30 noon	Q007
12:30 noon	-	1:30 pm	Lunch
1:30 pm	-	3:00 pm	Technical Session 4
3:00 pm	-	3:45 pm	CDC Template
3:45 pm	-	4:15 pm	Break
4:15 pm	-	5:00 pm	Q105
5:00 pm			Wrap-up and closure

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Key Workshop Dates

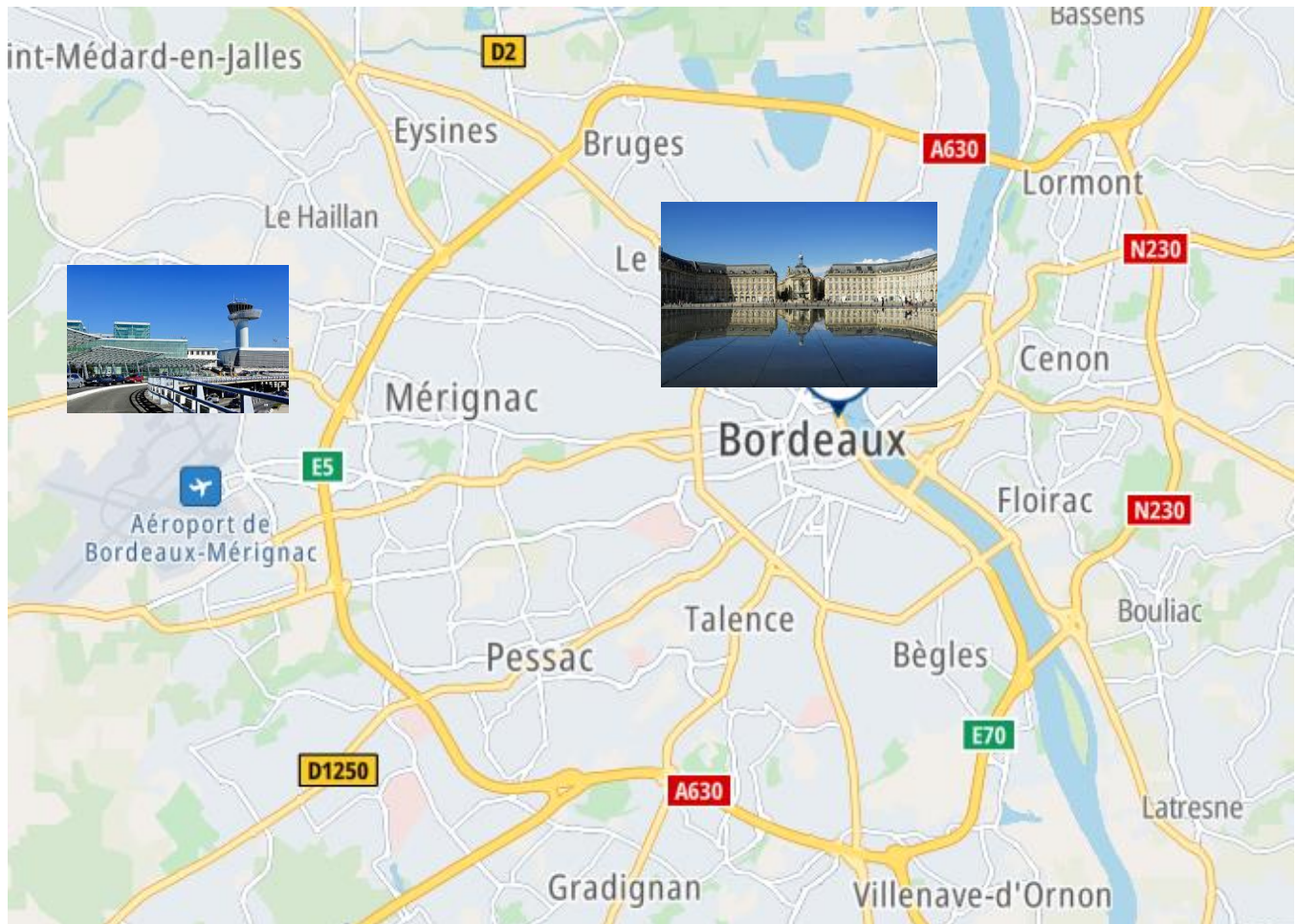
Call for Presentations	May 19, 2025
Registration Start	May 19, 2025
Abstract Submittal Deadline	August 11, 2025
Presentation Selection & Final Agenda	September 8, 2025
Final Copy of Presentation Due	October 3, 2025
Workshop Begins	October 8, 2025

Recording devices (video and/or audio) are prohibited at the workshop

Lodging: It is advised to make hotel room reservations in time.

Ground Transportation: Car rental, taxi service and public transportation are available at International Airport "Bordeaux-Mérignac".

Directions: Palais de la Bourse is located at about 15 kilometers from Bordeaux International Airport and close to Bordeaux down town (see map below).



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